

SOT648-1

plastic ball grid array package; 225 balls; body 27 x 27 x 1.55 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA225
Package type industry code	BGA225
Package style descriptive code	BGA (ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
JEITA package outline code	ED-7311-9A
Mounting method type	S (surface mount)
Issue date	24-1-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	26.8	-	27	27.2	mm
E	package width	26.8	-	27	27.2	mm
A	seated height	[tbd]	-	2.32	2.32	mm
A ₂	package height	1.42	-	1.55	1.64	mm
n ₂	actual quantity of termination	-	-	225	-	



2. Package outline

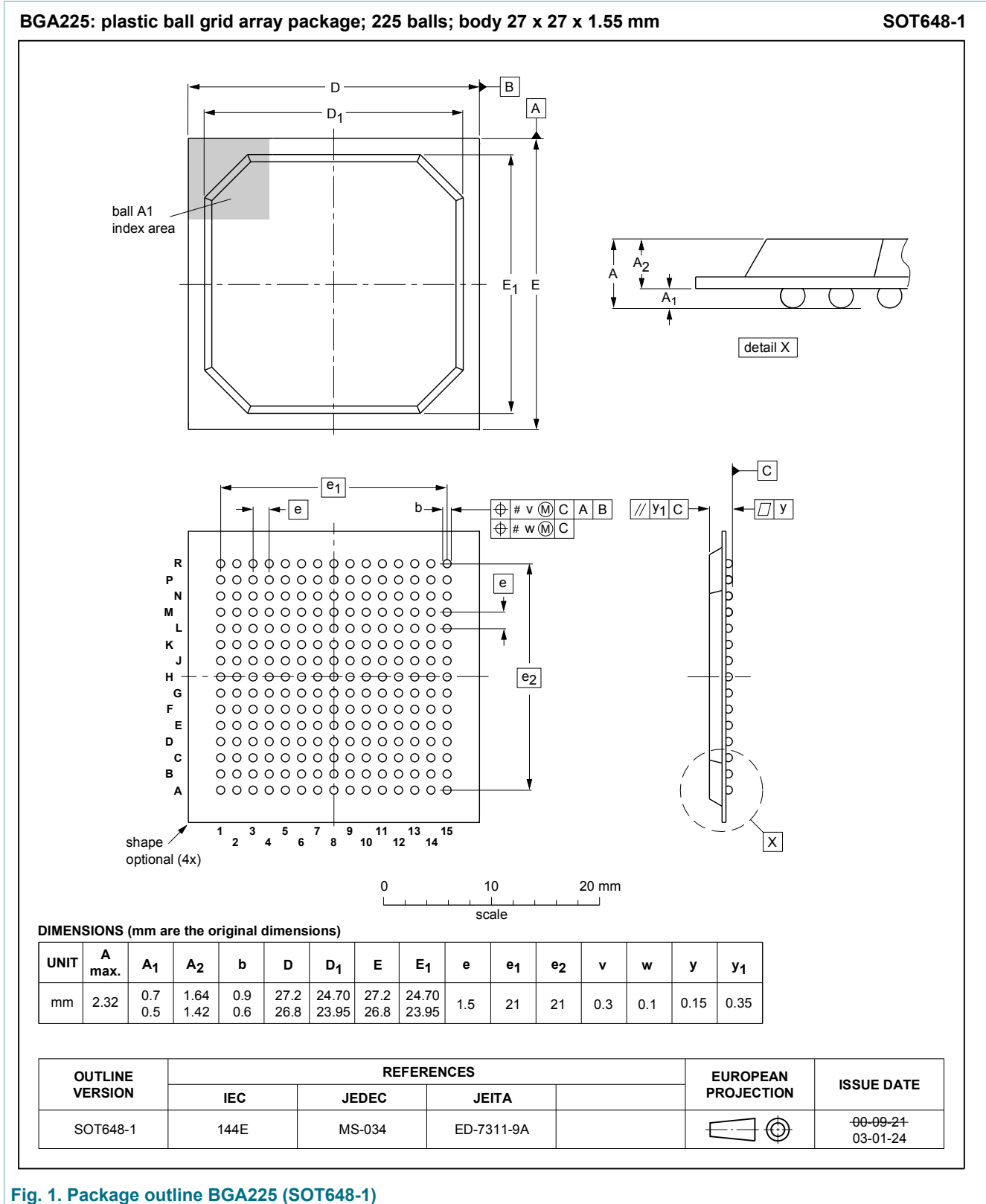
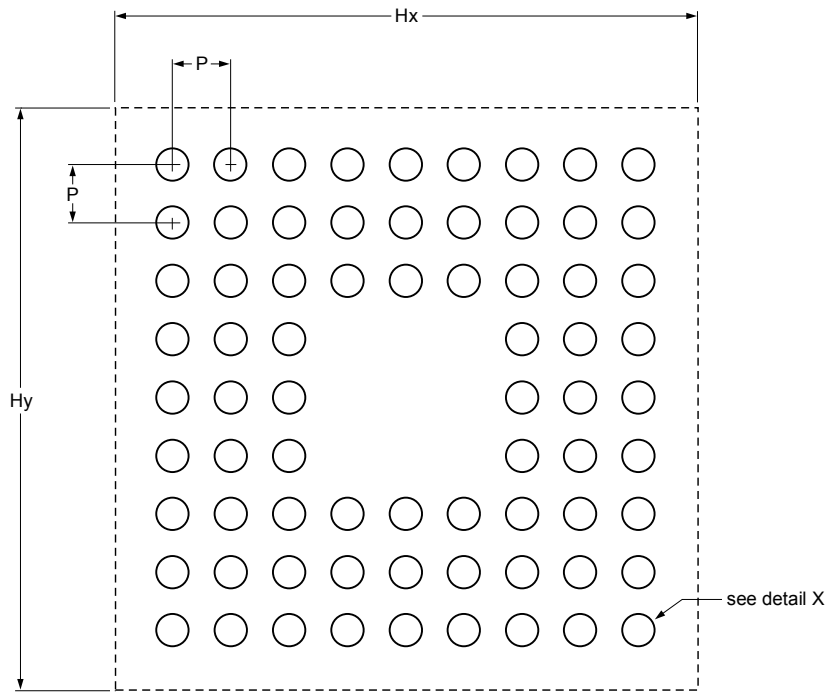


Fig. 1. Package outline BGA225 (SOT648-1)




3. Soldering

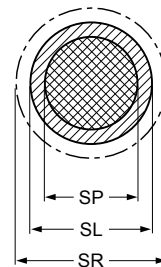
Footprint information for reflow soldering of BGA225 package

SOT648-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- solder resist



detail X

Dimensions in mm

P	SL	SP	SR	Hx	Hy
1.50	0.750	0.650	0.900	27.500	27.500

sot648-1_fr

Fig. 2. Reflow soldering footprint for BGA225 (SOT648-1)

4. Legal information

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